12042



256K (32K×8) UV ERASABLE PROM

- FAST ACCESS TIME:
 200ns MAX M27256-2F1
 250ns MAX M27256F1/M27256F6/M27256-25F1
 300ns MAX M27256-3F1/M27256-30F1
 450ns MAX M27256-4F1/M27256-4F6/M27256-45F1
- 0 to 70°C STANDARD TEMPERATURE RANGE
- -40 to +85°C EXTENDED TEMPERATURE RANGE
- SINGLE +5V POWER SUPPLY
- LOW STANDBY CURRENT (40mA MAX)
- TTL COMPATIBLE
- ◆ ±10% V_{CC} TOLERANCE AVAILABLE

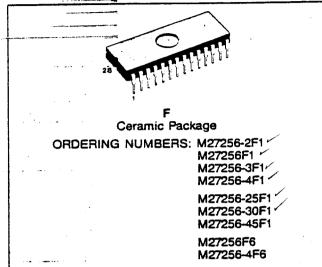


and pinout.

The M27256 is a 262,144-bit ultraviolet erasable and electrically programmable read only memory (EPROM). It is organized as 32.768 words by 8 bits and manufactured using SGS' NMOS-E3 process. The M27256 with its single +5V power supply and with an access time of 200ns, is ideal for use with high performance +5V microprocessor such as Z8°, Z80° and Z8000™. The M27256 has an important feature which is to separate the output control, Ouptut Enable (OE) from the Chip Enable control (CE). The OE control eliminate bus contention in multiple bus microprocessor systems.

The M27256 also features a standby mode which reduces the power dissipation without increasing access time. The active current is 100mA while the maximum standby current is only 40 mA, a 60% saving. The standby mode is achieved by appling a TTL-high signal to the CE input. The M27256 enables implementation of new, advanced systems with firmware intensive architectures.

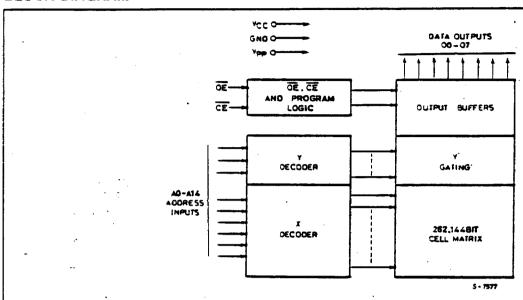
The combination of the M27256's high density, and new advanced microprocessors having megabit addressing capability provides designers with opportunities to engineer user-friendly, high reliability, high-performance systems. The M27256 large storage capability enables it to function as a high density software carrier. Entire operating systems, diagnostics, high-level language programs and specialized application software can reside in a M27256 directly on a system's memory bus. This permits immediate microprocessor access and execution of software and eliminates the need for time consuming disk accesses and downloads. The M27256 has an "Electronic Signature" that allows programmers to automatically identify device type



	PIN C	ONNECTIONS	
	Vpp :	28] Vcc	
	A12 2	27 1 A14	
	A7 [] 3	26 A13	l
}	1	25 A A B	
	A6 U4	24 A9	
	A5 [] 5		
	A4 [] 6	23[] A11	
	A3 🗓 7	25 ∐ <u>0</u> E	
	A2 []8	21 A10	
	A1 [9	20 T CE	
	AG [10	19 07	
-	00 (11	18] 06	
	01 12	17]] 05	
	02 [13	<u>. 16</u>] 04	
	GND 814	15] 03	•
	<u> </u>	S - 757.6	
			-
	Pli	N NAMES	
A0-A14	ADDRE	SS INPUT	
CE	CHIP E	NABLE INPUT	. ·
ŌĒ	OUTPU	IT ENABLE INPUT	
00-07	DATA II	NPUT/OUTPUT	



BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
VI	All Input or Output voltages with respect to ground	+6.25 to −0.6	٧
Vpp	Supply voltage with respect to ground	+14 to -0,6	٧
Tamb	.Ambient temperature under bias /F1 /F6	- 10 to +80 - 50 to +95	ဗ
T _{stg}	Storage temperature range	- 65 to +125	°င
	Voltage on pin 24 with respect to ground	+13.5 to -0.6	٧

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating on and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

OPERATING MODES

PINS	CE (20)	OE (22)	A9 (24)	A0 (10)	Vpp (1)	V _{CC} . (28)	OUTPUTS (11-13, 15-19)
READ	V _{IL}	Vie	X	Х	Vcc	Vcc	DOUT
OUTPUT DISABLE	۷ال	V _{iH}	X	X	Vcc	Vcc	HIGH Z
STANDBY	ViH	Х	X	X	Vcc	Vcc	HIGH Z
PROGRAM	V _{IL}	V _{IH}	X	Х	Vpp	Vcc	DiN
VERIFY	V _{iH}	VIL	X	· X	Vpp	Vcc	Dout
OPTIONAL VERIFY	V _I L	V _{IL}	X	X	Vpp	Vcc	DOUT
PROGRAM INHIBIT	V _{IH}	V _{iH}	X	X	Vpp	Vcc	HIGH Z
ELECTRONIC SIGNATURE	V _I L V _I L	V _{IL} V _{IL}	V _H V _H	V _{IL} V _{IH}	Vcc Vcc	Vcc Vcc	MAN.CODE DEV.CODE

NOTE: X can be VIH or VIL

 $V_{H} = 12V \pm 0.5V$

READ OPERATION DC AND AC CONDITIONS

	F1/-2F1 -3F1/-4F1	-25F1/-30F1/ -45F1	F6/ - 4F6
Operating Temperature Range	0 to 70°C	0 to 70°C	-40 to 85°C
V _{CC} Power Supply (1,2)	5V (±5%)	5V ±10%	5V €5%
V _{PP} Voltage (2)	VPP = VCC	Vpp = VCC	V _{PP} = V _{CC}

DC AND OPERATING CHARACTERISTICS

		·			Unit	
Symbol	Parameter	Test Conditions	Min.	Typ. (3)	Max.	Unit
ILI ·	Input Load Current	V _{IN} = 5.5V			10	μΑ
اده	Output Leakage Current	V _{OUT} = 5.5V			10	μΑ
IPP1(2)	Vpp Current Read Standby	Vpp = 5.5V			5	mA
ICC1(2)	V _{CC} Current Standby	CE=VIH		20	40	- тА
(CC2(2)	VCC Current Active	CE=OE=VIL Vpp=VCC		45	100	mA
VIL	Input Low Voltage		-0.1		+ 0.8	V
VIH	Input High Voltage		2.0		V _{CC} +1	V
VOL	Output Low Voitage	I _{OL} =2.1 mA	,	·	0.45	V
VOH	Output High Voltage	I _{OH} = -400 μA	2.4			V
Vpp(2)	Vee Read Voltage	V _{CC} =5V ±0.25V	3.8		Vcc	V

AC CHARACTERISTICS

		Test	27256-2		27256-25 / 27256		27256-30 / 27256-3		27256-45 / 27256-4		Unit
Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Min	Max	
tACC	Address to Output Delay	CE = OE = VIL		200	•	250	J	300	, .	450	ns
t _{CE}	CE to Output Delay	OE = VIL		200		250		300		450	ns
^t OE	OE to Output Delay	CE = VIL		75		100		120		150	ns
t _{DF(4)}	OE High to Output Float	CE = VIL	0	55	0	60	0	105	0	130	ns
tон	Output Hold from Address CE or OE Whichever Occurred First	CE = OE = VIL	0		0		0		0		ns

CAPACITANCE(5) (Tamb = 25°C, f = 1 MHz)

Symbol	Parameter -	Test Conditions	Min.	Тур.	Max.	Unit
CIN	Input Capacitance	V _{IN} =0V		4	6	ρF
COUT	Output Capacitance	V _{OUT} =0V		. 8	12	ρF

5. This parameter is only sampled and not 100% tested.

V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after V_{PP}.
 V_{PP} may be connected directly to V_{CC} except during programming. The supply current would than be the sum of l_{CC} and l_{PP1}.
 Typical values are for T_{amb} = 25°C and nominal supply voltages.
 This parameter is only sampled and not 100% tested. Output Float is defined as the point where data is no longer driven-see the point where data is no longer driven-see. timing diagram.



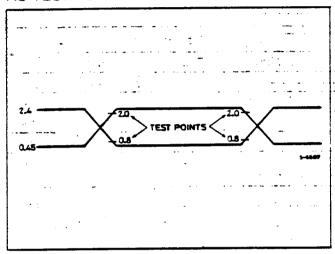
AC TEST CONDITIONS

Output Load: 100pF+1TTL Gate Input Rise and Fall Times: ≤ = 20ns Input Pulse Levels: 0.45 to 2.4V

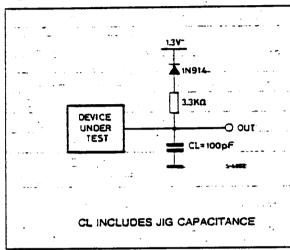
Timing Measurement Reference Levels: Inputs 0.8 and 2V

Outputs 0.8 and 2V

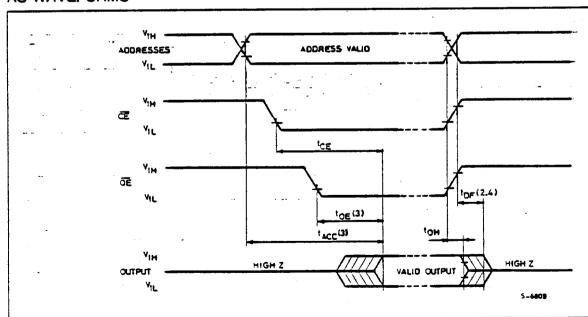
AC TESTING INPUT/OUTPUT WAVEFORM



AC TESTING LOAD CIRCUIT



AC WAVEFORMS



- 1. Typical values are for $T_{amb} = 25$ °C and nominal supply voltage.
- 2. This parameter is only sampled and not 100% tested.
- 3. OE may be delayed up to tACC toE after the falling edge CE without impact on tacc.

 4. toF is specified from OE or CE whichever occurs first.

DEVICE OPERATION

The eight modes of operations of the M27256 are listed in the Operating Modes. A single 5V power supply is required in the read mode. All inputs are TTL levels except for V_{PP} and 12V on A9 for Electronic Signature.

READ MODE

The M27256 has two control function, both of which must be logically satisfied in order to obtain data at the outputs. Chip Enable (CE) is the power control and should be used for device selection. Output Enable (OE) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (t_{ACC}) is equal to delay from CE to output (t_{CE}). Data is available at the outputs after the falling edge of OE, assuming that CE has been low and addresses have been stable for at least t_{ACC}-t_{OE}-

STANDBY MODE

The M27256 has a standby mode which reduces the maximum active power current from 100 mA to 40 mA. The M27256 is placed in the standby mode by applying a TTL high signal to the CE input. When in the standby mode, the outputs are in a high impedance state, independent of the OE input.

TWO LINE OUTPUT CONTROL

Because EPROMs are usually used in larger memory arrays, the product features a 2 line control function which accommodates the use of multiple memory connection. The two line control function allows:

- a) the lowest possible memory power dissipation
- b) complete assurance that output bus contention will not occur.

For the most efficient use of these two control lines, CE should be decoded and used as the primary device selecting function, while OE should be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in their low power standby mode and that the output pins are only active when data is desired from a particular memory device.

SYSTEM CONSIDERATIONS

The power switching characteristics of NMOS-E3 EPROMs require careful decoupling of the devices

the supply current, I_{CC}, has three segments that are of interest to the system designer: the standby current level, the active current level, and transient current peaks that are produced by the falling and rising edges of CE. The magnitude of this transient current peaks is dependent on the output capacitive and inductive loading of the device. The associated transient voltage peaks can be suppressed by complying with the two line output control and by properly selected decoupling capacitors. It is recommended that a 1 µF ceramic capacitor be used on every device between V_{CC} and GND. This should be a high frequency capacitor of low inherent inductance and should be placed as close to the device as possible. In addition, a 4.7 µF bulk electrolytic capacitors should be used between VCC and GND for every eight devices. The bulk capacitor should be located near where the power supply is connected to the array. The purpose of the bulk capacitor is to overcome the voltage droop caused by the inductive effects of PCB traces.

PROGRAMMING

Caution: exceeding 13V on pin 1 (V_{PP}) will damage the M27256.

When delivered, and after each erasure, all bits of the M27256 are in the "1" state. Data is introduced by selectively programming "0s" into the desired bit locations. Although only "0s" will be programmed, both "1s" and "0s" can be present in the data word. The only way to change a "0" to a "1" is by ultraviolet light erasure. The M27256 is in the programming mode when V_{PP} input is at 12.5V and CE and is at TTL low. The data to be programmed is applied 8 bits in parallel to the data output pins. The levels required for the address and data inputs are TTL.

FAST PROGRAMMING ALGORITHM

Fast Programming Algorithm rapidly programs M27256 EPROMs using an efficient and reliable method suited to the production programming environment. Programming reliability is also ensured as the incremental program margin of each bytes is continually monitored to determine when it has been successfully programmed. A flowchart of the M27256 Fast Programming Algorithm is shown on the last page. The Fast Programming Algorithm utilizes two different pulse types: initial and overprogram. The duration of the initial CE pulse (s) is one millisecond, which will than be followed by a



longer overprogram pulse of length 3Xmsec. (X is an iteration counter and is equal to the number of the initial one millisecond pulses applied to a particular M27256 location), before a correct verify occurs. Up to 25 one-millisecond pulses per byte are provided for before the over program pulse is applied. The entire sequence of program pulses and byte verifications is performed at $V_{CC} = 6V$ and $V_{PP} = 12.5V$. When the Fast Programming cycle has been completed, all bytes should be compared to the original data with $V_{CC} = V_{PP} = 5V$.

PROGRAM INHIBIT

Programming of multiple M27256s in parallel with different data is also easily accomplished. Except for \overline{CE} , all like inputs (including \overline{OE}) of the parallel M27256 may be common. A TTL low pulse applied to a M27256's \overline{CE} input, with V_{PP} at 12.5V, will program that M27256. A high level \overline{CE} input inhibits the other M27256s from being programmed.

PROGRAM VERIFY

A verify should be performed on the programmed bits to determine that they were correctly programmed. The verify is accomplished with OE at V_{IL} , \overline{CE} at V_{IH} and V_{PP} at 12.5V.

OPTIONAL VERIFY

The optional verify may be performed instead of the verify mode. It is performed with OE at V_{IL} , CE at V_{IL} (as opposed to the standard verify which has CE at V_{IH}), and V_{PP} at 12.5V. The outputs will three-state according to the signal presented to OE. Therefore, all devices with $V_{PP} = 12.5V$ and $OE = V_{IL}$ will present data on the bus independent of the CE state. When parallel programming several devices which share the common bus, V_{PP} should be lowered to V_{CC} (=6V) and the normal read mode used to execute a program verify.

ELECTRONIC SIGNATURE

The Electronic Signature mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment for the pur-

pose of automatically matching the device to b programmed with its corresponding programmin algorithm. This mode is functional in the 25° ±5°C ambient temperature range that is require when programming the M27256. To activate this mode, the programming equipment must forc 11.5V to 12.5V on address line A9 (pin 24) of th M27256. Two identifier bytes may than be sequent ed from the device outputs by toggling address lin A0 (pin 10) from VIL to VIH. All other address line must be held at VIL during Electronic Signatur mode. Byte 0 (A0 = V_{IL}) represents the manufact turer code and byte 1 (A0 = V_{IH}) the device iden tifier code. For the SGS M27256, these two ider tifier bytes are given below. All identifiers for manufacturer and device codes will possess od parity, with the MSB (07) defined as the parity bi

ERASURE OPERATION

The erasure characteristic of the M27256 is suc that erasure begins when the cells are exposed t light with wavelengths shorter than approximatel 4000 Angstrom ${f A}$. It should be noted that sunligh and some type of fluorescent lamps hav wavelengths in the 3000-4000 A range. Data show that constant exposure to room level fluorescen lighting could erase a typical M27256 in about years, while it would take approximately 1 week to cause erasure when expose to direct sunlight. the M27256 is to be exposed to these type of lighting conditions for extended periods of time, is suggested that opaque labels to put over the M27256 window to prevent unintentional erasure The recommended erasure procedure for the M27256 is exposure to short wave ultraviolet light which has wavelength 2537 A. The integrated dos (i.e. UV intensity x exposure time) for erasure should be a minimum of 15 W-sec/cm². The erasure time with this dosage is approximately 1 to 20 minutes using an ultraviolet lamp with 1200 μ W/cm² power rating. The M27256 should be place ed within 2.5 cm (1 inch) of the lamp tubes during the erasure. Some lamps have a filter on their tube which should be removed before erasure.

ELECTRONIC SIGNATURE MODE

PINS	A0 (10)	07 (19)	O6 (18)	O5 (17)	O4 (16)	O3 (15)	O2 (13)	01 (12)	O0 (11)	Hex Data
Manufacturer code	VIL	0	0	1	0	0	- 0	0	0	20
Device code	V _{!H}	0	0	0	0	0	1	0	0	04

PROGRAMMING OPERATION (T_{amb} = 25°C ±5°C, $V_{CC}^{(1)}$ = 6V ±0.25V, $V_{PP}^{(1)}$ = 12.5V ±0.3V

DC AND OPERATING CHARACTERISTIC:

:	Parameter .	Test Conditions		Unit		
Symbol		(See note 1)	Min.	Typ.	Max.	Oint
اں	Input Current (All Inputs)	VIN = VIL or VIH			10	μΑ
۷۱۲	Input Low Level (All Inputs)		-0.1		0.8	V
VIH	Input High Level		2.0		Vcc+1	V
VOL	Output Low Voltage During Verify	I _{OL} =2.1 mA	·-		0.45	V
VOH	Output High Voltage During Verify	I _{OH} = -400 μA	2.4	•		٧
lcc2	V _{CC} Supply Current (Program & Verify)		·		100	mA
lpp2	Vpp Supply Current (Program)	CE=VIL			.50	mA
V _{ID}	A9 Electronic Signature Voltage	·	11.5		12.5	V

AC CHARACTERISTICS

•	Parameter	Test Conditions		_	Unit	
Symbol		(See note 1)	Min.	Тур.	Max.	Jim
tAS	Address Setup Time		2	•	1	μS
^t OES	OE Setup Time	, and the additional section of the section of	2			μS
tos	Data Setup Time		2			μS
t _{AH}	Address Hold Time		_ o		-	μS
^t DH	Data Hodi Time		2			μS
tDFP(4)	Output Enable Output Float Delay		0		130	ns
tves	Vpp Setup Time		2		•	μs
tvcs	V _{CC} Setup Time		2			μS
tpw	CE Initial Program Pulse Width	(see Note 3)	0.95	1.0	1.05	ms
topw	CE Overprogram Pulse Width	(see Note 2)	2.85		78.75	ms
^l OE	Data Valid from OE				150	ns

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V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after V_{PP}.

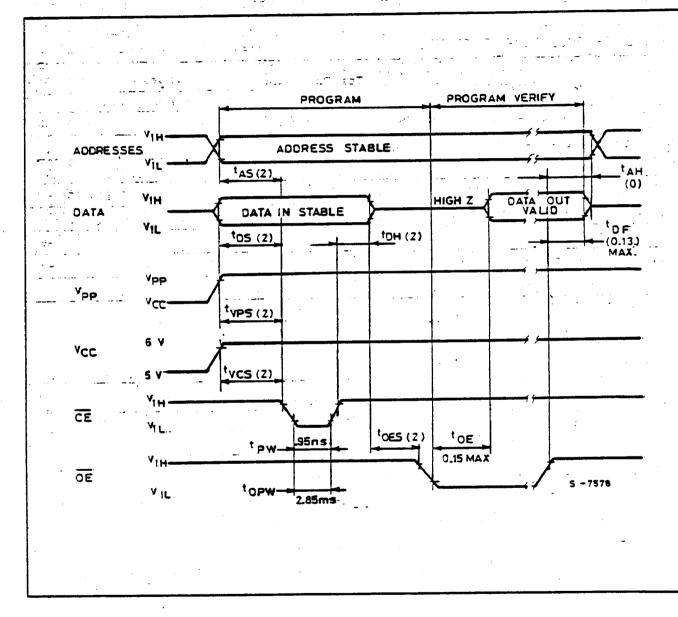
The length of the overprogram pulse may vary from 2.85msec to 78.75msec as a function of the iteration counter value X. Initial Program Pulse width tolerance is 1msec ±5%.

This parameter is only sampled and not 100% tested.

Output Float is defined as the point where data is no longer driven (see timing diagram).



PROGRAMMING WAFEFORMS



All times shown in () are minimum and in usec unless otherwise specified.

The input timing reference level is 0.8V for a V_{IL} and 2V for a V_{IH}

to and to per are characteristics of the device but must be accommodated by the programmer

When programming the M27256 a 0.1 µF capacitor is required across V_{PP} and GROUND to suppress spurious voltage transients while the device but must be accommodated by the programming the M27256 a 0.1 µF capacitor is required across V_{PP} and GROUND to suppress spurious voltage transients while the device but must be deviced across V_{PP} and GROUND to suppress spurious voltage transients while the device but must be deviced across V_{PP} and GROUND to suppress spurious voltage transients while the device but must be accommodated by the programming the M27256 a 0.1 µF capacitor is required across V_{PP} and GROUND to suppress spurious voltage transients while the device but must be accommodated by the programming the M27256 a 0.1 µF capacitor is required across V_{PP} and GROUND to suppress spurious voltage transients. can damage the device.

